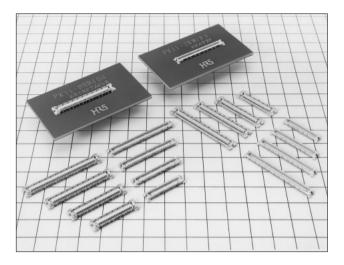
0.5mm Pitch Connectors with Ground Plate for 2mm Board-to-Board Connections

FX11L Series



Features

1. Low Profile Design

The board to board mating height of 2 mm suits smaller, thinner case designs.

2. Improved Transmission Efficiency Between Boards

Transmission characteristics have been improved through a design that fixes ground plates to both sides of the header and receptacle.

3. 10 Signal:1 Ground Arrangement

Signal and ground are arranged in a ratio of 10:1 with the ground plate SMT connected to the board. The ground stability achieved serves to reduce noise.

4. Reinforced Fittings for Added Solder Weld Strength

Reinforced fittings provide greater adhesion to the board,protecting against peeling. The unique connector design provides a connection between the fitting and the ground plate for a stronger ground.

5. Suited to High-Density Applications

The signal contact pitch of 0.5mm produces a smaller connector utilizing less board area for mounting.

6. Structure Prevents Solder Wicking

A solder gap has been designed into the contact SMT portion to prevent solder wicking.

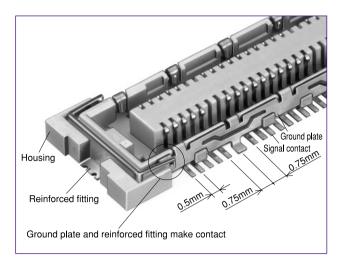
7. Optional Ground Plate

An alternate style without the ground plate is available. The space provided by the ground plate removal has been filled with additional signal contacts.

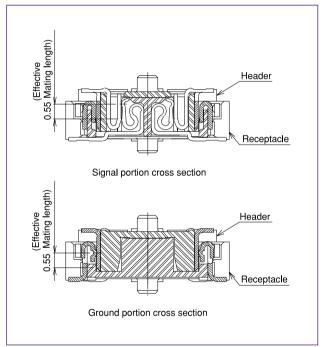
Note: The thickness of the solder paste is not included in the 2 mm board-to-board stack height.

Applications

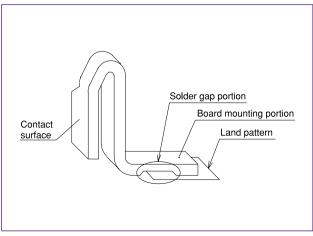
Notebook computers, PDA, and other miniature electronic equipment.



•Cross-Section of Mating



Detailed Figure of Solder Gap



Product Specifications

	Rated current	0.3 A (Note 1)	Operating temperature range	-55 to 85℃	Storage temperature range	-10 to +60°C (Note 2)
Rating	Rated voltage	50 V AC	Operating humidity range	Relative humidity 95% or less	Storage humidity range	40 to 70% (Note 2)
				(No condensation)		

Item	Requirements	Conditions
1. Insulation resistance	100 MΩ or greater	Measured at 100 V DC
2. Voltage proof	No flashover or breakdown	150 V AC applied for one minute
3. Contact resistance	60 mΩ or less	Measured at 100 mA
4. Vibration	No electrical discontinuity for 1µs or greater No damage, cracks, or parts looseness	Frequency: 10 to 55 Hz, amplitude of 0.75 mm in 3 directions, 10 cycles each
5. Shock	No electrical discontinuity for 1µs or longer No damage, cracks, or parts looseness	Acceleration of 490 m/s ² , 11ms duration, sine half-wave waveform, for 3 cycles in the both directions of each of the 3 axes
6. Damp heat (Steady state)	Contact resistance of 70 m Ω or less, insulation resistance of 100 M Ω or greater, no damage, cracks, or parts looseness	Temperature of 40°C, humidity of 90 to 95%, duration 96 h
7. Rapid change of temperature	Contact resistance of 70 m Ω or less, insulation resistance of 100 M Ω or greater, no damage, cracks, or parts looseness	Temperature: -55 [°] C → 15 to 35 [°] C → 85 [°] C → 15 to 35 [°] C Time: 30 min. → 2 to 3 min. → 30 min. → 2 to 3 min. for 5 cycles
8. Insertion/ Withdrawal life	Contact resistance of 70 m Ω or less No damage, cracks, or parts looseness	50 times
9. Resistance to soldering heat	No melting of resin portion which affects performance	Reflow: At the recommended temperature profile Soldering iron temperature: 300°C for 3 seconds

Note 1: Please contact us when connector application exceeds 0.3 A rated current.

Note 2: The term storage refers to an unused products prior to board mounting (including packing materials) that is being kept for a long period. The operating temperature and humidity range are applied to the non-conducting condition following board assembly.

Note 3: The aforementioned specifications are representative of this series. For information on specific parts, confirm with Sales Office.

Materials

Part	Material		Process			
Insulator	LCP resin	Beige		UL94V-0		
Contonto	Copper alloy	Header	Engagement Area: Gold plating of 0.1μ m			
Contacts	Phosphor bronze	Receptacle	Termination Area: Flash plating			
Ground plate	Phosphor bronze	Solder plating				
Reinforced fitting		Tip plating				
Reinforced plate	Reinforced plate Phosphor bronze Tin plating					

Note : The black dots on the insulater will not affect performance.

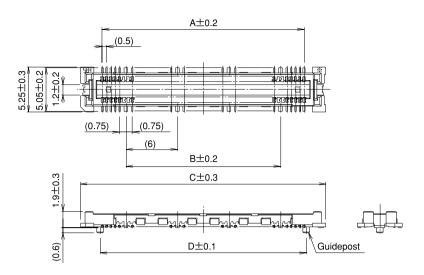
Product Number Configuration

Please use this information to discern the product specifications from the product number codes. To order, please select from the product number codes listed in tables on pages 3 to 6 of this catalog.

ype With Ground Plate	FX	11L	# -	*	-	/*	-	SV (* *)		
	0	2	8		6	-		o		
pe Without Ground Plate	FX	11L	# -	* F			/ ((* *)		
	0	2	3	4	6	_	6			
Series name : FX							6	Connector type		
Ø Series No. : 11L							P : Header			
8 Form Symbol A	With gu	ide post						S : Receptacle		
В	Without	guide po	ost				6	Contact form		
4 Number of contact	s Type wi	th ground	plate					SV : Straight SMT		
	Signal/0	Ground:60	0/6, 80/8	, 100/10), 120/	'12	7	Blank: Tray packaging (Without pick-and-place tape)		
	Туре и	vithout gro	ound					(21): Embossed tape packaging (Without pick-and-place tape)		
	Signal:	68, 92, 1 <i>1</i>	16, 140					(22): Embossed tape packaging (With pick-and-place tape)		
	eignan							(),		

Headers with Ground Plate





	Draduat Na	Number of Contacts			P		D	E	Natas
HRS No.	Product No.	Signal	Ground	A	В	С	D		Notes
CL573-0002-7-* *	FX11LA- 60P/ 6-SV (**)	60	6	17.5	12	22.6	18	19.4	
CL573-0003-0-* *	FX11LA- 80P/ 8-SV (**)	80	8	23.5	18	28.6	24	25.4	With guidenests
CL573-0004-2-* *	FX11LA-100P/10-SV (* *)	100	10	29.5	24	34.6	30	31.4	With guideposts
CL573-0005-5-* *	FX11LA-120P/12-SV (* *)	120	12	35.5	30	40.6	36	37.4	
CL573-0012-0-* *	FX11LB- 60P/ 6-SV (**)	60	6	17.5	12	22.6	_	19.4	
CL573-0013-3-* *	FX11LB- 80P/ 8-SV (* *)	80	8	23.5	18	28.6	_	25.4	Without guidenests
CL573-0014-6-* *	FX11LB-100P/10-SV (* *)	100	10	29.5	24	34.6	_	31.4	Without guideposts
CL573-0015-9-* *	FX11LB-120P/12-SV (* *)	120	12	35.5	30	40.6	_	37.4	

[Specifications number] - * *, (* *)

Blank: Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

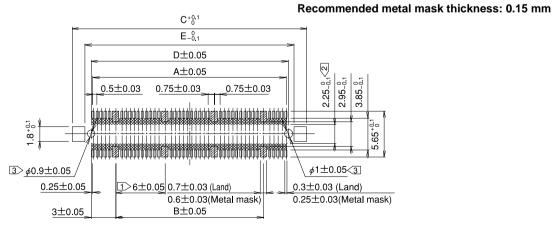
(22) : Embossed tape packaging (With pick-and-place tape)

Note 1: There is no polarity in terms of board mounting for this product.

Note 2: The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3: Please order embossed tape packaged items by the reel. (One reel holds 1,000 pieces.)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

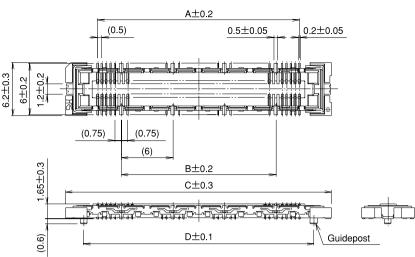


Note $\boxed{1}$ Cross-hatched portions, totaling n places, indicate the ground circuits.

- 2 The cross-hatched area 🖾 inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
- $\boxed{3}$ Not required in products without guideposts.

■Receptacles with Ground Plate





HRS No. Product No.		Number o	Number of Contacts		В	<u> </u>		Е	F	Notes	
	Product No.	Signal	Ground	A	D	C	D		Г	NOLES	
CL573-0102-1-**	FX11LA- 60S/ 6-SV (**)	60	6	17.5	12	25	20.8	25.4	22.2		
CL573-0103-4-**	FX11LA- 80S/ 8-SV (**)	80	8	23.5	18	31	26.8	31.4	28.2	With guideposts	
CL573-0104-7-* *	FX11LA-100S/10-SV (**)	100	10	29.5	24	37	32.8	37.4	34.2	With guideposts	
CL573-0105-7-**	FX11LA-120S/12-SV (**)	120	12	35.5	30	43	38.8	43.4	40.2		
CL573-0112-5-**	FX11LB- 60S/ 6-SV (**)	60	6	17.5	12	25	-	25.4	22.2		
CL573-0113-8-**	FX11LB- 80S/ 8-SV (**)	80	8	23.5	18	31	-	31.4	28.2	Without guideposts	
CL573-0114-0-**	FX11LB-100S/10-SV (**)	100	10	29.5	24	37	-	37.4	34.2	Without guideposts	
CL573-0105-3-* *	FX11LB-120S/12-SV (**)s	120	12	35.5	30	43	-	43.4	40.2		

[Specifications number] - * *, (* *)

Blank: Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

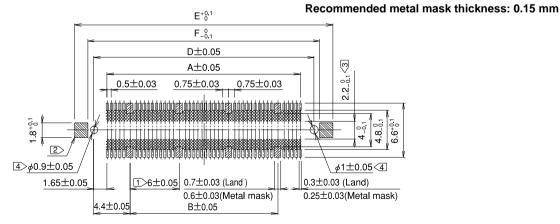
(22) : Embossed tape packaging (With pick-and-place tape)

Note 1: There is no polarity in terms of board mounting for this product.

Note 2: The coplanarity of this product's SMT leads is 0.1mm or less.

Note 3: Please order embossed tape packaged items by the reel. (One reel holds 1,000 pieces.)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)



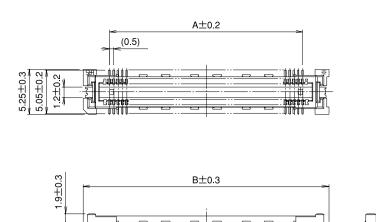
Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

- 2 Cross-hatched portions, totaling 2 places, indicate the reinforced fittings.
- 3 The cross-hatched area inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
- $\boxed{4}$ Not required in products without guideposts.

(0.6)

Headers without Ground Plate





C±0.1

Guidepost

HRS No.	Product No.	Number of Contacts Signal	A	В	С	D	Notes
CL573-0042-1-* *	FX11LA- 68P-SV (**)	68	16.5	22.6	18	19.4	
CL573-0043-4-* *	FX11LA- 92P-SV (* *)	92	22.5	28.6	24	25.4	With guideposts
CL573-0044-7-* *	FX11LA-116P-SV (* *)	116	28.5	34.6	30	31.4	With guideposts
CL573-0045-0-* *	FX11LA-140P-SV (* *)	140	34.5	40.6	36	37.4	
CL573-0052-5-* *	FX11LB- 68P-SV (* *)	68	16.5	22.6	_	19.4	
CL573-0053-8-* *	FX11LB- 92P-SV (* *)	92	22.5	28.6	_	25.4	Without guidenests
CL573-0054-0-* *	FX11LB-116P-SV (* *)	116	28.5	34.6	_	31.4	Without guideposts
CL573-0055-3-* *	FX11LB-140P-SV (* *)	140	34.5	40.6	_	37.4	

[Specifications number] - * *, (* *)

Blank: Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

(22) : Embossed tape packaging (With pick-and-place tape)

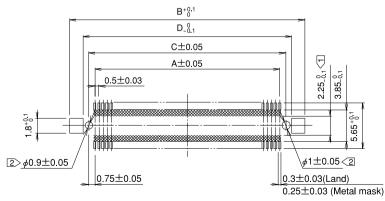
Note 1: There is no polarity in terms of board mounting for this product.

Note 2: The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3: Please order embossed tape packaged items by the reel. (One reel holds 1,000 pieces.)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

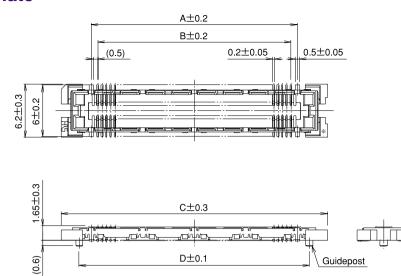
Recommended metal mask thickness: 0.15 mm



- Note 1 The cross-hatched area 🖾 inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
 - $\boxed{2}$ Not required in products without guideposts.

Receptacles without Ground Plate





HRS No.	Product No.	Number of Contacts Signal	А	В	С	D	Notes
CL573-0142-6-* *	FX11LA- 68S-SV (* *)	68	18	16.5	25	20.8	
CL573-0143-9-* *	FX11LA- 92S-SV (**)	92	24	22.5	31	26.8	With guideposts
CL573-0144-1-* *	FX11LA-116S-SV (**)	116	30	28.5	37	32.8	
CL573-0145-4-* *	FX11LA-140S-SV (**)	140	36	34.5	43	38.8	
CL573-0152-0-* *	FX11LB- 68S-SV (**)	68	18	16.5	25	-	
CL573-0153-2-* *	FX11LB- 92S-SV (**)	92	24	22.5	31	_	Without guideposts
CL573-0154-5-* *	FX11LB-116S-SV (**)	116	30	28.5	37	—	
CL573-0155-8-* *	FX11LB-140S-SV (**)	140	36	34.5	43	_	

[Specifications number] - * *, (* *)

Blank: Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

(22) : Embossed tape packaging (With pick-and-place tape)

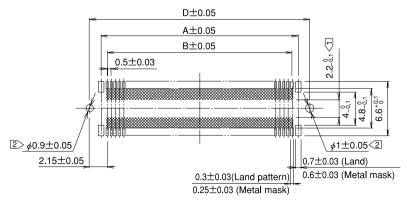
Note 1: There is no polarity in terms of board mounting for this product.

Note 2: The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3: Please order embossed tape packaged items by the reel. (One reel holds 1,000 pieces.)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

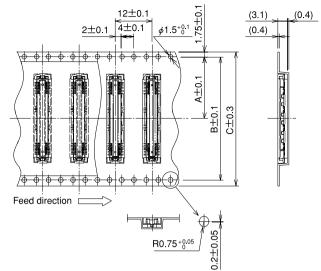
Recommended metal mask thickness: 0.15 mm



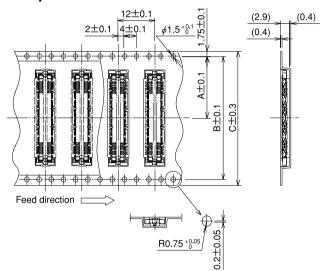
Note 1 The cross-hatched area inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width. 2 Not required in products without guideposts.

Embossed Carrier Tape Dimensions

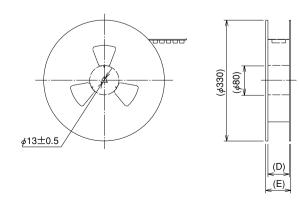
Headers



Receptacles



Reel Packaging Dimensions



Insertion Connector	A	В	С	D	Е	
FX11L#- 60P/ 6-SV	20.2	40.4	44	45.5	50.6	
FX11L#- 80P/ 8-SV	20.2	40.4	44	45.5	50.6	
FX11L#-100P/10-SV	26.2	52.4	56	59	64	
FX11L#-120P/12-SV	20.2	52.4	50	59	04	
FX11L#- 68P -SV	20.2	40.4	44	45.5	50.5	
FX11L#- 92P -SV	20.2	40.4	44	45.5	50.5	
FX11L#-116P -SV	26.2	52.4	56	59	64	
FX11L#-140P -SV	20.2	52.4	50	-09	04	

Note 1: There is no polarity in terms of embossed tape packaging for this product.

Note 2: Left figure is representative of products with ground plates.

Insertion Connector	A	В	С	D	Е
FX11L#- 60S/ 6-SV	20.2	40.4	44	45.5	50.6
FX11L#- 80S/ 8-SV	20.2	40.4	44	45.5	50.6
FX11L#-100S/10-SV	26.2	52.4	56	59	64
FX11L#-120S/12-SV	20.2	52.4	50	59	04
FX11L#- 68S -SV	20.2	40.4	44	45.5	50.5
FX11L#- 92S -SV	20.2	40.4	44	45.5	50.5
FX11L#-116S -SV	26.2	52.4	56	59	64
FX11L#-140S -SV	20.2	52.4	50	-09	04

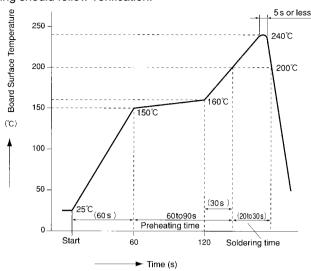
Note 1: There is no polarity in terms of embossed tape packaging for this product.

Note 2: Left figure is representative of products with ground plates.



Recommended Temperature Profile

This temperature profile is a reference for the setting conditions described below. It will differ depending on conditions and so mounting should follow verification.



Applicable Conditions							
Reflow method	:	IR reflow					
Solder	:	Cream type 63Sn/37Pb					
		(Flux component of 9wt%)					
Test substrate	:	Glass epoxy 85 x 110 x 1.6mm					
Metal mask thickness	:	0.15mm					

This temperature profile is a recommendation. Conditions may change somewhat depending on the type of cream solder and the amount.

Washing Conditions

Organic Solvent Washing

Solvent	Room temperature washing	Heated washing
IPA (Isopropyl alcohol)	Yes	Yes
HCFC (Hydrochlorofluorocarbon)	Yes	Yes

Water Type Washing

When using water type cleaning agents (e.g., terpene, and alkali saponifiers), select the cleaning agent based on the documentation issued by the various manufacturers of cleaning agents which describes the effects on metals and resins. Be careful that parts are not left with moisture remaining on them.

Washing Precautions

Residual flux or cleaning agent on the contacts when washing with organic solvents or water type cleaners can give rise to the deterioration of electrical performance. In this regard it is important to check whether a thorough washing has been performed.

Connector Handling Precautions

1. Allowable Creepage Dimensions at Time of Mating

The effective coupling length of this product is 0.55 mm for the signal portion and the ground portion. The creepage of the header and receptacle at the time of mating should be within 0.18 mm of the completely coupled condition.

2. Retension of Boards

Avoid the support of boards by connectors alone and adopt a board locking measure that does not rely on the connectors.

3. Solder Repair

Flux may rise as far as the contact portion of the connector depending on the flux coating and other factors at the time of repair. This will cause poor contact reliability; therefore, before use, the aforementioned washing conditions should be taken into consideration prior to connector washing.

4. Miscellaneous

Note that excessive twisting while inserting or withdrawing connectors will cause damage.

•The shade of the molded items may vary somewhat depending on the manufacturing lot; however, this does not affect performance.



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